



HEXFET® POWER MOSFET

Provisional Data Sheet No. PD-9.429B

JANTX2N6794

JANTXV2N6794

[REF:MIL-PRF-19500/555]

[GENERIC:IRFF420]

N-CHANNEL

500 Volt, 3.0Ω HEXFET

HEXFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry achieves very low on-state resistance combined with high transconductance.

HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, and high energy pulse circuits, and virtually any application where high reliability is required.

Product Summary

Part Number	BV _{DSS}	R _{DSON}	I _D
JANTX2N6794			
JANTXV2N6794	500V	3.0Ω	1.5A

Features:

- Avalanche Energy Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed

Absolute Maximum Ratings

	Parameter	JANTX2N6794, JANTXV2N6794	Units
I _D @ V _{GS} = 10V, T _C = 25°C	Continuous Drain Current	1.5	A
I _D @ V _{GS} = 10V, T _C = 100°C	Continuous Drain Current	1.0	
I _{DM}	Pulsed Drain Current ①	6.0	
P _D @ T _C = 25°C	Max. Power Dissipation	20	W
	Linear Derating Factor	0.16	
V _{GS}	Gate-to-Source Voltage	±20	V
dv/dt	Peak Diode Recovery dv/dt ③	3.5	V/ns
T _J T _{TSG}	Operating Junction Storage Temperature Range	-55 to 150	°C
	Lead Temperature	300 (0.063 in. (1.6mm) from case for 10.5 seconds)	
	Weight	0.98 (typical)	

JANTX2N6794, JANTXV2N6794 Device

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	500	—	—	V	$V_{GS} = 0\text{V}, I_D = 1.0\text{ mA}$
$\Delta BVDSS/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.43	—	$\text{V}/^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 1.0\text{ mA}$
RDS(on)	Static Drain-to-Source On-State Resistance	—	—	3.0	Ω	$V_{GS} = 10\text{V}, I_D = 1.0\text{A}$ ④
		—	—	3.45		$V_{GS} = 10\text{V}, I_D = 1.5\text{A}$
VGS(th)	Gate Threshold Voltage	2.0	—	4.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
gfs	Forward Transconductance	1.0	—	—	S (Ω)	$V_{DS} > 15\text{V}, I_{DS} = 1.0\text{A}$ ④
IDSS	Zero Gate Voltage Drain Current	—	—	25	μA	$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0\text{V}$
		—	—	250		$V_{DS} = 0.8 \times \text{Max Rating}$ $V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$
IGSS	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20\text{V}$
IGSS	Gate-to-Source Leakage Reverse	—	—	-100		$V_{GS} = -20\text{V}$
Qg	Total Gate Charge	7.3	—	16.7	nC	$V_{GS} = 10\text{V}, I_D = 1.5\text{A}$
Qgs	Gate-to-Source Charge	0.1	—	3.0		$V_{DS} = \text{Max. Rating} \times 0.5$ see figures 6 and 13
Qgd	Gate-to-Drain ("Miller") Charge	3.7	—	8.7		
Id(on)	Turn-On Delay Time	—	—	40	ns	$V_{DD} = 250\text{V}, I_D = 1.5\text{A},$ $R_G = 7.5\Omega, V_{GS} = 10\text{V}$
t _r	Rise Time	—	—	30		
t _{d(off)}	Turn-Off Delay Time	—	—	60		
t _f	Fall Time	—	—	30		see figure 10
L _D	Internal Drain Inductance	—	5.0	—	nH	Measured from the drain lead, 6mm (0.25 in.) from package to center of die.
L _S	Internal Source Inductance	—	15	—		Measured from the source lead, 6mm (0.25 in.) from package to source bonding pad.
C _{iss}	Input Capacitance	—	350	—	pF	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}$
C _{oss}	Output Capacitance	—	80	—		$f = 1.0\text{ MHz}$
C _{rss}	Reverse Transfer Capacitance	—	35	—		see figure 5

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	1.5	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
I _{SM}	Pulse Source Current (Body Diode) ④	—	—	6.0		
V _{SD}	Diode Forward Voltage	—	—	1.2	V	$T_J = 25^\circ\text{C}, I_S = 1.5\text{A}, V_{GS} = 0\text{V}$ ④
t _{rr}	Reverse Recovery Time	—	—	900	ns	$T_J = 25^\circ\text{C}, I_F = 1.5\text{A}, dI/dt \leq 100\text{A}/\mu\text{s}$
Q _{RR}	Reverse Recovery Charge	—	—	5.9	μC	$V_{DD} \leq 50\text{V}$ ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{thJC}	Junction-to-Case	—	—	6.25	K/W	
R _{thJA}	Junction-to-Ambient	—	—	175		Typical socket mount

2

JANTX2N6794, JANTXV2N6794 Device

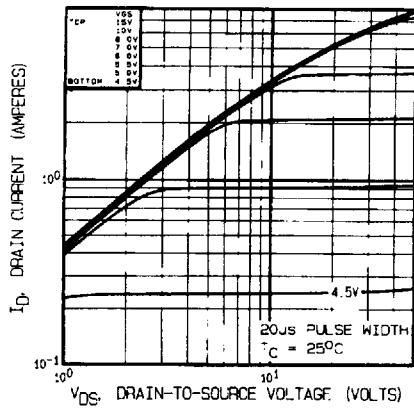


Fig. 1 — Typical Output Characteristics
 $T_C = 25^\circ\text{C}$

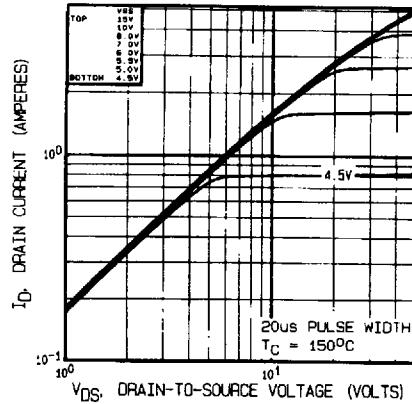


Fig. 2 — Typical Output Characteristics
 $T_C = 150^\circ\text{C}$

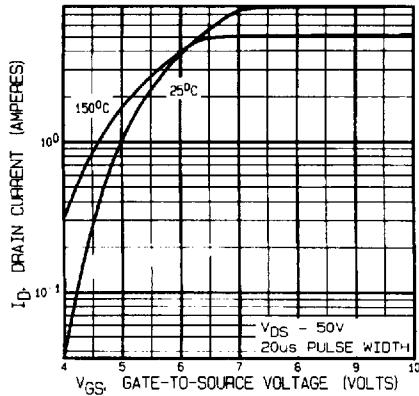


Fig. 3 — Typical Transfer Characteristics

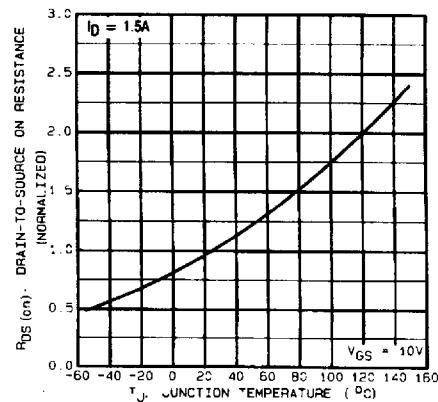


Fig. 4 — Normalized On-Resistance Vs. Temperature

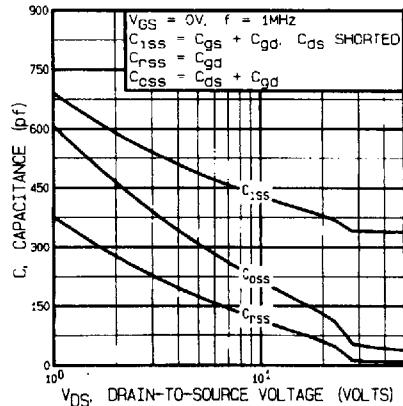


Fig. 5 — Typical Capacitance Vs. Drain-to-Source Voltage

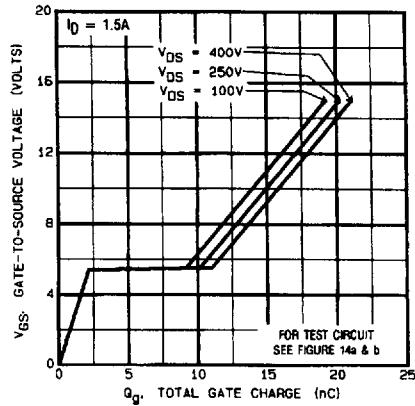


Fig. 6 — Typical Gate Charge Vs. Gate-to-Source Voltage

JANTX2N6794, JANTXV2N6794 Device

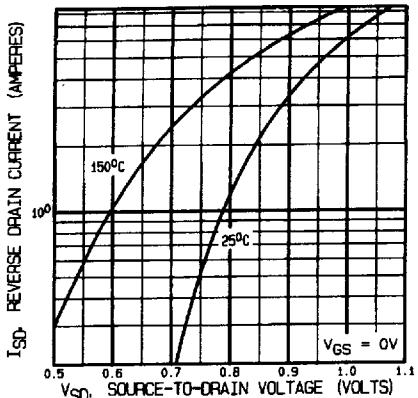


Fig. 7 — Typical Source-to-Drain Diode Forward Voltage

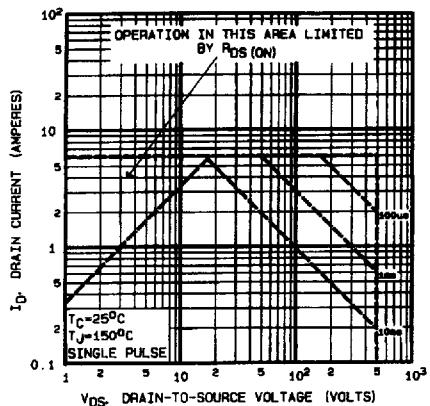


Fig. 8 — Maximum Safe Operating Area

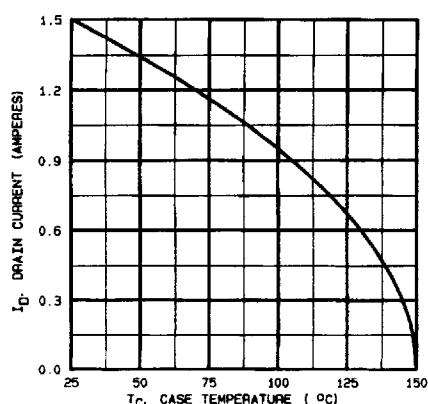


Fig. 9 — Maximum Drain Current Vs. Case Temperature

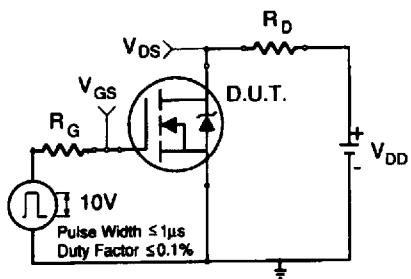


Fig. 10a — Switching Time Test Circuit

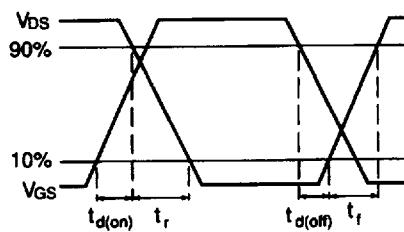


Fig. 10b — Switching Time Waveforms

JANTX2N6794, JANTXV2N6794 Device

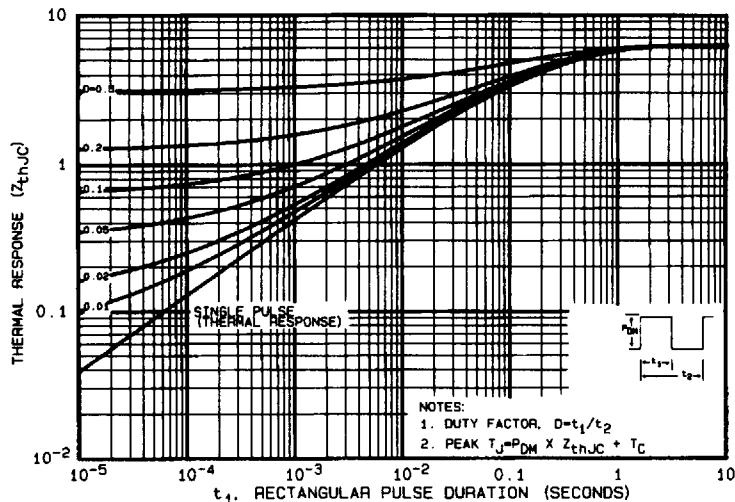


Fig. 11 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

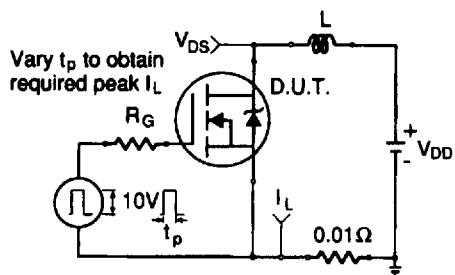


Fig. 12a — Unclamped Inductive Test Circuit

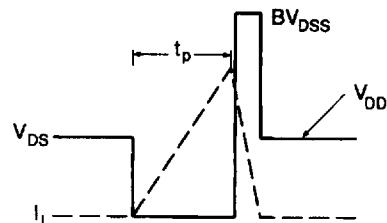


Fig. 12b — Unclamped Inductive Waveforms

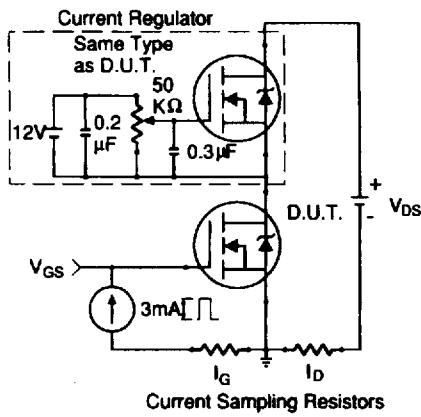


Fig. 13a — Gate Charge Test Circuit

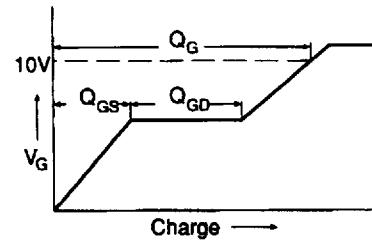


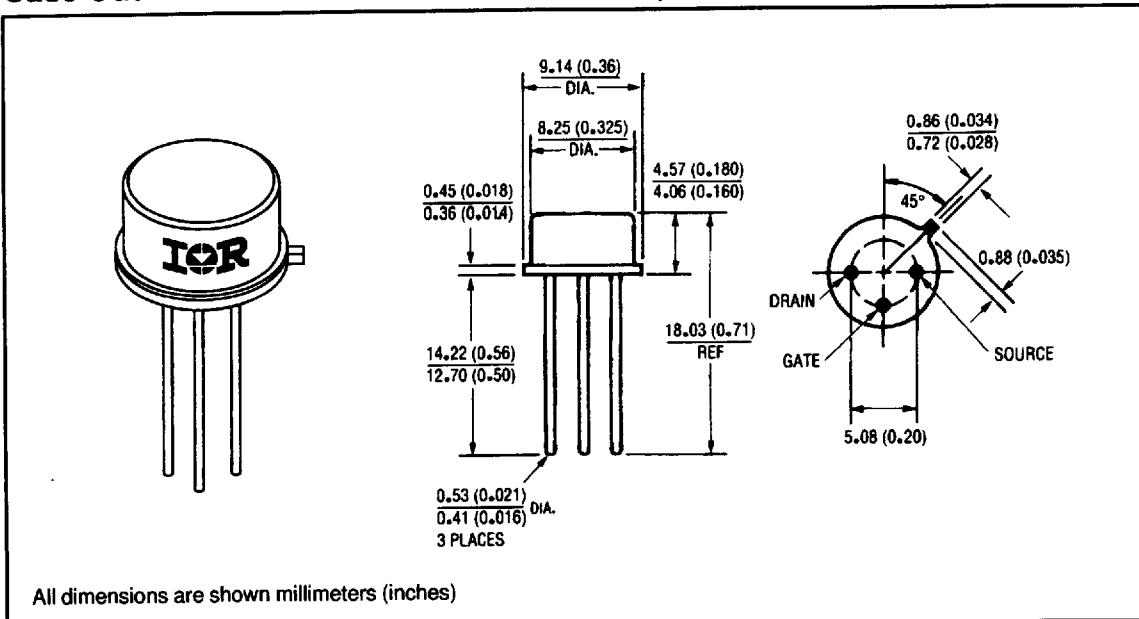
Fig. 13b — Basic Gate Charge Waveform

JANTX2N6794, JANTXV2N6794 Device

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
(see figure 11)
- ② @ V_{DD} = 50V, Starting T_J = 25°C,
EAS = [0.5 * L * (I_L²) * {BV_{DSS}/(BV_{DSS}-V_{DD})}]
Peak I_L = 1.5A, V_{GS} = 10V, 25 ≤ R_G ≤ 200Ω

- ③ I_{SD} ≤ 1.5A, di/dt ≤ 50A/μs,
V_{DD} ≤ BV_{DSS}, T_J ≤ 150°C
- ④ Pulse width ≤ 300 μs; Duty Cycle ≤ 2%
- ⑤ K/W = °C/W
W/K = W/°C

Case Outline and Dimensions — TO-205AF (Modified TO-39)



International
IR Rectifier

WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 322 3331
EUROPEAN HEADQUARTERS: Hurst Green, Oxted, Surrey RH8 9BB, UK Tel: ++ 44 1883 732020

IR CANADA: 7321 Victoria Park Ave., Suite 201, Markham, Ontario L3R 2Z8, Tel: (905) 475 1897

IR GERMANY: Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 6172 96590

IR ITALY: Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 11 451 0111

IR FAR EAST: K&H Bldg., 2F, 3-30-4 Nishi-Ikeburo 3-Chome, Toshima-Ki, Tokyo Japan 171 Tel: 81 3 3983 0086

IR SOUTHEAST ASIA: 315 Outram Road, #10-02 Tan Boon Liat Building, Singapore 0316 Tel: 65 221 8371

<http://www.irf.com/> Data and specifications subject to change without notice. 10/96

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Infineon manufacturer:

Other Similar products are found below :

[614233C](#) [648584F](#) [MCH3443-TL-E](#) [MCH6422-TL-E](#) [FDPF9N50NZ](#) [FW216A-TL-2W](#) [FW231A-TL-E](#) [APT5010JVR](#) [NTNS3A92PZT5G](#)
[IRF100S201](#) [JANTX2N5237](#) [2SK2464-TL-E](#) [2SK3818-DL-E](#) [FCA20N60_F109](#) [FDZ595PZ](#) [STD6600NT4G](#) [FSS804-TL-E](#) [2SJ277-DL-E](#)
[2SK1691-DL-E](#) [2SK2545\(Q,T\)](#) [D2294UK](#) [405094E](#) [423220D](#) [MCH6646-TL-E](#) [TPCC8103,L1Q\(CM](#) [367-8430-0972-503](#) [VN1206L](#)
[424134F](#) [026935X](#) [051075F](#) [SBVS138LT1G](#) [614234A](#) [715780A](#) [NTNS3166NZT5G](#) [751625C](#) [873612G](#) [IRF7380TRHR](#)
[IPS70R2K0CEAKMA1](#) [RJK60S3DPP-E0#T2](#) [RJK60S5DPK-M0#T0](#) [APT5010JVFR](#) [APT12031JFLL](#) [APT12040JVR](#) [DMN3404LQ-7](#)
[NTE6400](#) [JANTX2N6796U](#) [JANTX2N6784U](#) [JANTXV2N5416U4](#) [SQM110N05-06L-GE3](#) [SIHF35N60E-GE3](#)